

REMARKS

Claims 1-5, 8, 9 and 11-16 are all the claims pending in the application. Claims 1 and 8 have been amended to recite "wherein the cleaning layer has a tensile modulus of 10 MPa or more as determined according to JIS K7127 and exhibits an adhesive strength of 0.2N/10 mm width or less when peeled off a silicon wafer at an angle of 180° as determined according to JIS Z0237" based on, for example, pages 21 and 29 of the present specification.

Since the amendments raise no issues of new matter, entry of the above amendments is respectfully requested.

I. Response to Rejection of Claims 1-5, 8 and 9 under 35 U.S.C. § 103(a)

Claims 1-5, 8 and 9 are still rejected under 35 U.S.C. §103(a) as allegedly being unpatentable over Suzuura et al. (US Patent No. 6,066,404).

Applicants respectfully traverse the rejection for the reasons of record and the following reasons.

Independent claim 1 is directed to a cleaning sheet comprising a cleaning layer comprising a polyimide resin which is heat-resistant, and a releasable protective film laminated on the cleaning layer, wherein each of the relative intensities of the fragment ions of CH_3Si^+ , $\text{C}_3\text{H}_9\text{Si}^+$, $\text{C}_5\text{H}_{15}\text{Si}_2\text{O}^+$, $\text{C}_5\text{H}_{15}\text{Si}_3\text{O}_3^+$, $\text{C}_7\text{H}_{21}\text{Si}_3\text{O}_2^+$, CH_3SiO^- , $\text{CH}_3\text{SiO}_2^-$ and Si^+ in the cleaning layer, when the protective film is peeled off the cleaning layer, is 0.1 or less according to time-of-flight secondary ion mass spectrometry, relative to C_2H_3^+ in the case of positive ion or O^- in the case of negative ion, wherein the cleaning layer has a tensile modulus of 10 MPa or more as determined according to JIS K7127 and exhibits an adhesive strength of 0.2N/10 mm width or less when peeled off a silicon wafer at an angle of 180° as determined according to JIS Z0237.

Independent claim 8 is directed to a carrying member with a cleaning function, comprising a carrying member and a cleaning layer comprising a polyimide resin which is heat-

resistant provided on at least one side of the carrying member, wherein each of the relative intensities of the fragment ions of CH_3Si^+ , $\text{C}_3\text{H}_9\text{Si}^+$, $\text{C}_5\text{H}_{15}\text{Si}_2\text{O}^+$, $\text{C}_5\text{H}_{15}\text{Si}_3\text{O}_3^+$, $\text{C}_7\text{H}_{21}\text{Si}_3\text{O}_2^+$, CH_3SiO^- , $\text{CH}_3\text{SiO}_2^-$ and Si^+ in the cleaning layer is 0.1 or less according to time-of-flight secondary ion mass spectrometry, relative to C_2H_3^+ in the case of positive ion or O^- in the case of negative ion, wherein the cleaning layer has a tensile modulus of 10 MPa or more as determined according to JIS K7127 and exhibits an adhesive strength of 0.2N/10 mm width or less when peeled off a silicon wafer at an angle of 180° as determined according to JIS Z0237.

It is respectfully submitted that Suzuura does not disclose that the cleaning layer of claims 1 and 8. Specifically, the Examiner considers the base layer of Suzuura as corresponding to the cleaning layer of claims 1 and 8. However, Suzuura does not disclose, teach or suggest that the base layer has a tensile modulus of 10 MPa or more as determined according to JIS K7127 and exhibits an adhesive strength of 0.2N/10 mm width or less when peeled off a silicon wafer at an angle of 180° as determined according to JIS Z0237.

Thus, Suzuura does not teach or suggest the cleaning sheet of claim 1 or the cleaning member of claim 8.

In addition, each of claims 2-5 and 9 depend, directly or indirectly, from claim 1 or 8, and thus, it is respectfully submitted that these claims are patentable for at least the same reasons as claim 1 or 8.

Furthermore, regarding claim 4, Suzuura does not disclose the claimed structure. That is, in claim 4, the adhesive layer is on the side of the support opposite to the side where the cleaning layer is formed. In contrast, in Example 1 of Suzuura, the heat-sealing layer is formed between the base layer 2 and the inner protective layer 6, which the Examiner considers to be the cleaning layer and the support, respectively. Thus, it is respectfully submitted that claim 4 is patentable over Suzuura for an additional reason.

In view of the above, it is respectfully submitted that claims 1-5, 8 and 9 are patentable over Suzuura and withdrawal of the rejection is respectfully requested.

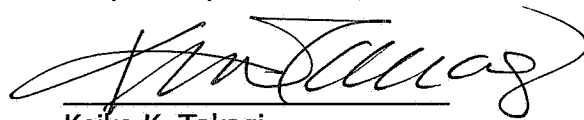
II. Conclusion

For the foregoing reasons, reconsideration and allowance of claims 1-5, 8, 9 and 11-16 is respectfully requested.

If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



Keiko K. Takagi
Registration No. 47,121

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON DC SUGHRUE/265550

65565

CUSTOMER NUMBER

Date: September 21, 2007